



Material Content Data Sheet



Sales Product Name		TLE7738G		Issued		25. September 2017		
MA#		MA001015600						
Package		PG-DSO-52-4		Weight*		871.89 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	27.549	3.16	3.16	31597	31597
leadframe	inorganic material	phosphorus	7723-14-0	0.073	0.01		84	
	non noble metal	zinc	7440-66-6	0.293	0.03		336	
	non noble metal	iron	7439-89-6	5.854	0.67		6714	
wire	non noble metal	copper	7440-50-8	237.701	27.26	27.97	272629	279763
	noble metal	gold	7440-57-5	3.083	0.35	0.35	3536	3536
	encapsulation	organic material	carbon black	1333-86-4	1.163	0.13		1334
encapsulation	plastics	epoxy resin	-	53.484	6.13		61343	
	inorganic material	silicondioxide	60676-86-0	526.706	60.42	66.68	604099	666776
leadfinish	non noble metal	tin	7440-31-5	7.508	0.86	0.86	8611	8611
plating	noble metal	silver	7440-22-4	0.935	0.11	0.11	1072	1072
glue	plastics	epoxy resin	-	1.885	0.22		2161	
	noble metal	silver	7440-22-4	5.654	0.65	0.87	6484	8645
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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